

LAMINATION PROCESS AND STRUCTURE OF HIGH LAYOUT DENSITY SUBSTRATE

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ABSTRACT OF THE INVENTION

10 A lamination process and structure of a high layout density
substrate is disclosed. The lamination process comprises the
following steps. First of all, a plurality of laminating layers are
individually formed, wherein each laminating layer has a first dielectric
layer, a plurality of first vias and a patterned conducting layer. Next,
15 a bottom layer having a second dielectric layer and a plurality of
second vias is formed. Then, the laminating layers and the bottom
layer are stacked. Finally, the laminating layers and the bottom layer
are laminated simultaneously to form a multiplayer substrate at one
time.

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